Silicon N Channel MOS Type (U-MOSII)/Silicon Epitaxial Schottky Barrier Diode

# SSM5H01TU

#### DC-DC Converter

Unit: mm

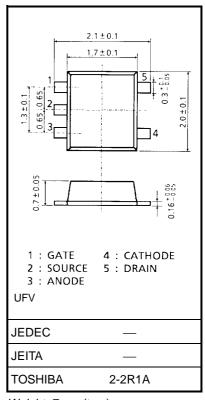
- Combined Nch MOSFET and Schottky Diode into one Package.
- Low RDS (ON) and Low VF

# Maximum Ratings (Ta = 25°C) MOSFET

Characteristics		Symbol	Rating	Unit	
Drain-Source voltage		$V_{DS}$	30	V	
Gate-Source voltage		$V_{GSS}$	±20	V	
Drain current	DC	I <sub>D</sub>	1.4	Α	
	Pulse	I <sub>DP</sub> (Note 2)	2.8	^	
Drain power dissipation		P <sub>D</sub> (Note 1)	0.5	W	
		t = 10s	0.8	VV	
Channel temperature		T <sub>ch</sub>	150	°C	

# Maximum Ratings (Ta = 25°C) SCHOTTKY DIODE

Characteristics	Symbol	Rating	Unit
Maximum (peak) reverse voltage	$V_{RM}$	25	V
Reverse voltage	$V_{R}$	20	V
Average forward current	Io	0.5	Α
Peak one cycle surge forward current (non-repetitive)	I <sub>FSM</sub>	2 (50 Hz)	Α
Junction temperature	Tj	125	°C



Weight: 7 mg (typ.)

# Maximum Ratings (Ta = 25°C) MOSFET, DIODE COMMON

Characteristics	Symbol	Rating	Unit
Storage temperature	T <sub>stg</sub>	-55~125	°C
Operating temperature	T <sub>opr</sub> (Note 3)	-40~100	°C

Note 1: Mounted on FR4 board

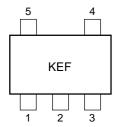
 $(25.4 \text{ mm} \times 25.4 \text{ mm} \times 1.6 \text{ t}, \text{ Cu pad: } 645 \text{ mm}^2)$ 

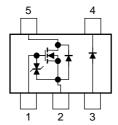
Note 2: The pulse width limited by max channel temperature.

Note 3: Operating temperature limited by max channel temperature and max junction temperature.

## Marking

# **Equivalent Circuit**





# **Handling Precaution**

When handling individual devices (which are not yet mounting on a circuit board), be sure that the environment is protected against electrostatic discharge. Operators should wear anti-static clothing and use containers and other objects that are made of anti-static materials.

The Channel-to-Ambient thermal resistance  $R_{th}$  (ch-a) and the drain power dissipation  $P_D$  vary according to the board material, board area, board thickness and pad area. When using this device, please take heat dissipation fully into account.

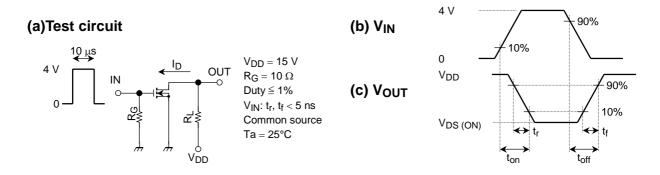
#### **MOSFET**

## **Electrical Characteristics (Ta = 25°C)**

Characteristic		Symbol	Test Condition	Min	Тур.	Max	Unit	
Gate leakage current		I <sub>GSS</sub>	$V_{GS} = \pm 16 \text{ V}, V_{DS} = 0$	_	_	±1	μΑ	
Drain-Source breakdown voltage		V (BR) DSS	$I_D = 1 \text{ mA}, V_{GS} = 0$	30	_	_	V	
		V (BR) DSX	$I_D = 1 \text{ mA}, V_{GS} = -20 \text{ V}$	15	_	_	v l	
Drain Cut-off current		I <sub>DSS</sub>	V <sub>DS</sub> = 30 V, V <sub>GS</sub> = 0	_	_	1	μΑ	
Gate threshold voltage		$V_{th}$	$V_{DS} = 5 \text{ V}, I_{D} = 0.1 \text{ mA}$	1.0	_	2.4	V	
Forward transfer admittance		Y <sub>fs</sub>	$V_{DS} = 5 \text{ V}, I_{D} = 0.7 \text{ A}$ (Note 4)	0.9	1.8	_	S	
Drain-Source ON resistance		R <sub>DS (ON)</sub>	$I_D = 0.7 \text{ A}, V_{GS} = 10 \text{ V}$ (Note 4)	_	140	200	<b>m</b> O	
			$I_D = 0.7 \text{ A}, V_{GS} = 4 \text{ V}$ (Note 4)	_	250	450	mΩ	
Input capacitance		C <sub>iss</sub>	V <sub>DS</sub> = 15 V, V <sub>GS</sub> = 0, f = 1 MHz	_	106	_	pF	
Reverse transfer capacitance		C <sub>rss</sub>	V <sub>DS</sub> = 15 V, V <sub>GS</sub> = 0, f = 1 MHz	_	15	_	pF	
Output capacitance		C <sub>oss</sub>	V <sub>DS</sub> = 15 V, V <sub>GS</sub> = 0, f = 1 MHz	_	28	_	pF	
Switching time	Turn-on time	t <sub>on</sub>	V <sub>DD</sub> = 15 V, I <sub>D</sub> = 0.7 A	_	18	_	- ns	
	Turn-off time	t <sub>off</sub>	$V_{GS} = 0~4~V,~R_{G} = 10~\Omega$		10	_		

Note 4: Pulse measurement

### **Switching Time Test Circuit**



#### **Precaution**

 $V_{th}$  can be expressed as voltage between gate and source when low operating current value is  $I_D$  = 100  $\mu A$  for this product. For normal switching operation,  $V_{GS}$  (on) requires higher voltage than  $V_{th}$  and  $V_{GS}$  (off) requires lower voltage than  $V_{th}$ .

(Relationship can be established as follows: VGS (off) < Vth < VGS (on))

Please take this into consideration for using the device.

 $V_{\mathrm{GS}}$  recommended voltage of 4.0V or higher to turn on this product.

# **Schottky Diode**

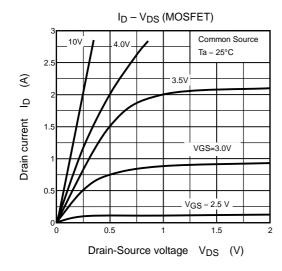
## Electrical Characteristics (Ta = 25°C)

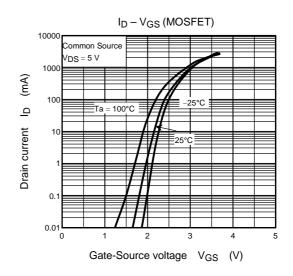
Characteristic	Symbol	Test Condition	Min	Тур.	Max	Unit
Forward voltage	V <sub>F (1)</sub>	I <sub>F</sub> = 0.3 A	_	0.38	0.45	V
	V <sub>F (2)</sub>	I <sub>F</sub> = 0.5 A	_	0.43	_	V
Reverse current	$I_{R}$	V <sub>R</sub> = 20 V	_	_	50	μΑ
Total capacitance	C <sub>T</sub>	V <sub>R</sub> = 0 V, f = 1 MHz	_	46	_	pF

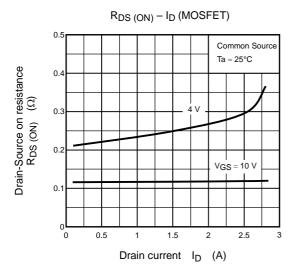
#### **Precaution**

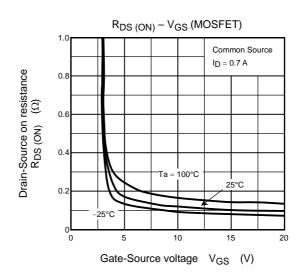
The schottky barrier diode of this product are having large-reverse-current-leakage characteristic compare to the other switching diodes. This current leakage and not proper operating temperature or voltage may cause thermal runaway. Please take forward and reverse loss into consideration when you design.

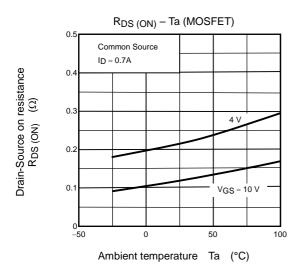
MOSFET Electrical Characteristics Graph

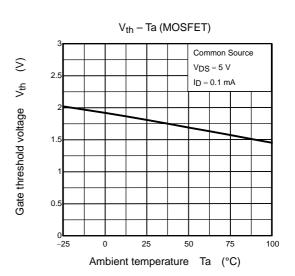


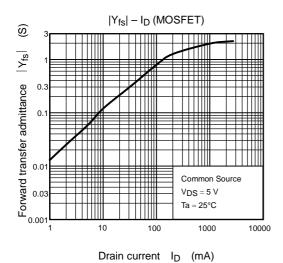


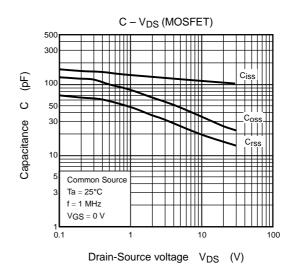


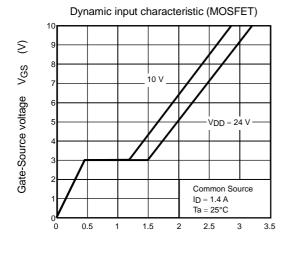




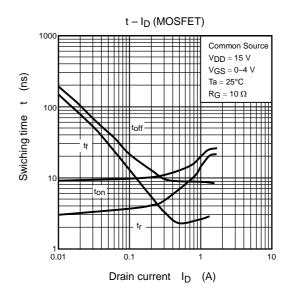


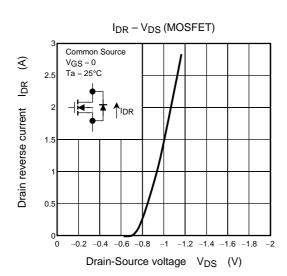






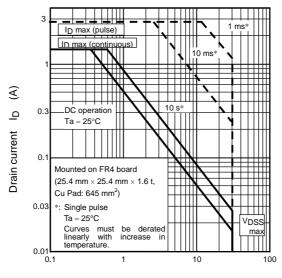
Total gate charge Qg (nC)



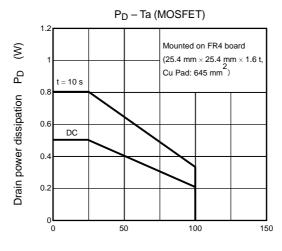


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Drain-Source voltage  $V_{DS}$  (V)

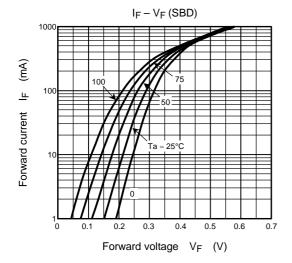


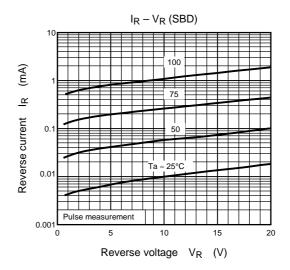
Ambient temperature Ta (°C)

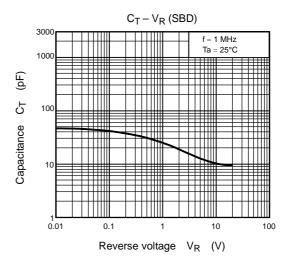
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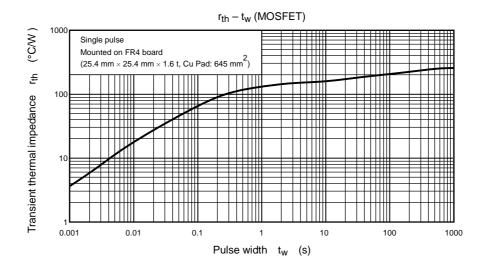
SBD Electrical Characteristics Graph

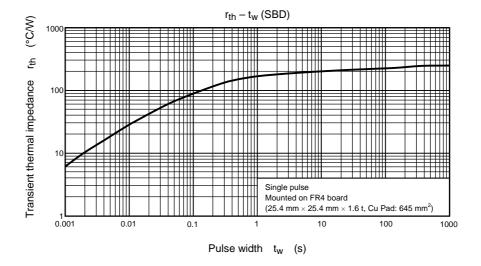






Transient thermal impedance Graph





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